L Number	Hits	Search Text	DB	Time stamp
1	1240	implant\$7 and blister and substrate	USPAT;	2004/09/10 13:24
	j		US-PGPUB;	
	ļ		EPO;	
	j		DERWENT;	1
	i		IBM_TDB	1
3	116	(implant\$7 and blister and substrate) and calibrat\$4	USPAT;	2004/09/10 12:00
		,	US-PGPUB;	
	ł		EPO;	1
	i		DERWENT;	1
	i		IBM_TDB	
4	1147	(implant\$7 and blister and substrate) and (dose or	USPAT;	2004/09/10 12:00
		dosage)	US-PGPUB;	
	i		EPO;	1
	i		DERWENT;	1
	l		IBM_TDB	1
5	110	((implant\$7 and blister and substrate) and calibrat\$4)	USPAT;	2004/09/10 12:00
	110	and ((implant\$7 and blister and substrate) and (dose or	US-PGPUB;	357, 10 12.00
}	i	dosage))	EPO;	
	i		DERWENT;	
	i		IBM_TDB	
6	3280	implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 12:00
	1200	substrate	US-PGPUB;	
	İ		EPO;	
	İ		DERWENT;	
	İ		IBM_TDB	
7	348	(implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 12:00
	510	substrate) and calibrat\$4	US-PGPUB;	=004071012:00
	İ	,	EPO;	
	İ		DERWENT;	1
	İ		IBM_TDB	1
8	2005	(implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 12:00
	2003	substrate) and (dose or dosage)	US-PGPUB;	_00 407/10 12:00
	İ	, and (mood of doouge)	EPO;	1
	İ		DERWENT;	1
	İ		IBM TDB	1
9	240	((implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 12:55
	210	substrate) and calibrat\$4) and ((implant\$7 and (blister	US-PGPUB;	=00407/1012:33
	İ	or blistering or bubble) and substrate) and (dose or	EPO;	
	Ì	dosage))	DERWENT;	
		<i>"</i>	IBM_TDB	
10	196	(((implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 12:58
	- / 0	substrate) and calibrat\$4) and ((implant\$7 and (blister	US-PGPUB;	_ = = = = = = = = = = = = = = = = = = =
		or blistering or bubble) and substrate) and (dose or	EPO;	Į į
		dosage))) and density	DERWENT;	
		· ///	IBM_TDB	
11	142	((((implant\$7 and (blister or blistering or bubble) and	USPAT;	2004/09/10 13:23
	. 14	substrate) and calibrat\$4) and ((implant\$7 and (blister	US-PGPUB;	= = = = = = = = = = = = = = = = = = = =
		or blistering or bubble) and substrate) and (dose or	EPO;	
		dosage))) and density) and imag\$5	DERWENT;	1
		5 , , , = ======= , , and magy	IBM TDB	
12	69	implant\$7 and blister and substrate and semiconductor	USPAT;	2004/09/10 15:17
	37	1 Shows and Substrate and Schillenductor	US-PGPUB;	200 407/10 13:17
			EPO;	į l
		<b>!</b>	DERWENT;	į l
			IBM_TDB	Į l
13	0	20020173872.URPN.	USPAT	2004/09/10 14:57
			JOLAI	2007/07/10 14:3/

14	173	implant\$7 and blister and calibrat\$5	USPAT;	2004/09/10 15:20
* *	1,,5	implanted, and proces and campiated	US-PGPUB;	200 405,10 13:20
			EPO;	·
			DERWENT;	
			IBM_TDB	
15	171	(implant\$7 and blister and calibrat\$5) not (implant\$7	USPAT;	2004/09/10 15:20
13	1/1	and blister and substrate and semiconductor)	US-PGPUB;	2004/09/10 13.20
:		and buster and substrate and semiconductor)	EPO;	
			DERWENT;	
1,,			IBM_TDB	0004/00/10 15 00
16	0	((implant\$7 and blister and calibrat\$5) not (implant\$7	USPAT;	2004/09/10 15:20
		and blister and substrate and semiconductor)) and	US-PGPUB;	
		semiconductor	EPO;	
			DERWENT;	
			IBM_TDB	
17	41	((implant\$7 and blister and calibrat\$5) not (implant\$7	USPAT;	2004/09/10 15:20
		and blister and substrate and semiconductor)) and silicon	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
18	380	implant\$7 and bubble and calibrat\$5	USPAT;	2004/09/10 15:20
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
19	380	(implant\$7 and bubble and calibrat\$5) not (implant\$7	USPAT;	2004/09/10 15:20
		and blister and substrate and semiconductor)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
20	81	(implant\$7 and bubble and calibrat\$5) and	USPAT;	2004/09/10 15:20
		semiconductor	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
22	13	((implant\$7 and bubble and calibrat\$5) and	USPAT;	2004/09/10 15:21
Í		semiconductor) not ((implant\$7 and bubble and	US-PGPUB;	
		calibrat\$5) and silicon)	EPO;	
			DERWENT;	
			IBM_TDB	
21	142	(implant\$7 and bubble and calibrat\$5) and silicon	USPAT;	2004/09/10 15:27
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
23	574	438/530	USPĀT;	2004/09/10 15:32
į			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
24	15	438/530 and (blister\$4 or bubbl\$4)	USPĀT;	2004/09/10 15:32
		· · · · · · ·	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	

25	12	(438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7	USPAT;	2004/09/10 15:32
		and bubble and calibrat\$5) and silicon) not ((implant\$7	US-PGPUB;	
		and bubble and calibrat\$5) and semiconductor) not	EPO;	
		(((implant\$7 and blister and calibrat\$5) not (implant\$7	DERWENT;	
		and blister and substrate and semiconductor)) and	IBM_TDB	
		silicon) not (implant\$7 and blister and substrate and		
		semiconductor)		
26	342	438/510	USPAT;	2004/09/10 15:33
			US-PGPUB;	
	1		EPO;	
			DERWENT;	
			IBM TDB	
27	15	438/510 and (blister\$4 or bubbl\$4)	USPAT;	2004/09/10 15:33
			US-PGPUB;	200.409/10 13.33
			EPO;	
			DERWENT;	
	:		IBM_TDB	
28	13	(438/510 and (blister\$4 or bubbl\$4)) not (438/530 and	USPAT;	2004/09/10 15:33
~0	] 13	(blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and	US-PGPUB;	2004/07/10 13:33
		calibrat\$5) and silicon) not ((implant\$7 and bubble and		
		calibrat\$5) and semiconductor) not (((implant\$7 and bubble and	EPO;	
			DERWENT;	
		blister and calibrat\$5) not (implant\$7 and blister and	IBM_TDB	
		substrate and semiconductor)) and silicon) not		
29	763	(implant\$7 and blister and substrate and semiconductor) 438/514	LICDATE	0004/00/10 15 41
29	/ 63	430/314	USPAT;	2004/09/10 15:41
•			US-PGPUB;	
			EPO;	
	i		DERWENT;	
30	42	490/514 1 /1-1 04	IBM_TDB	0004/00/10 15 40
30	42	438/514 and (blister\$4 or bubbl\$4)	USPAT;	2004/09/10 15:42
			US-PGPUB;	
			EPO;	
			DERWENT;	
0.1	۱ ا	(400/5) 4 1/11/2	IBM_TDB	
31	31	(438/514 and (blister\$4 or bubbl\$4)) not (438/510 and	USPAT;	2004/09/10 15:42
		(blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or	US-PGPUB;	
		bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5)	EPO;	
		and silicon) not ((implant\$7 and bubble and calibrat\$5)	DERWENT;	
		and semiconductor) not (((implant\$7 and blister and	IBM_TDB	
	]	calibrat\$5) not (implant\$7 and blister and substrate and		
	[	semiconductor)) and silicon) not (implant\$7 and blister		
0.0		and substrate and semiconductor)		
32	176	438/515	USPAT;	2004/09/10 15:43
			US-PGPUB;	
	]		EPO;	
			DERWENT;	
			IBM_TDB	
33	23	438/515 and (blister\$4 or bubbl\$4)	USPAT;	2004/09/10 15:43
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	

34	13	(438/515 and (blister\$4 or bubbl\$4)) not (438/514 and	USPAT;	2004/09/10 15:43
		(blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or	US-PGPUB;	
		bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not	EPO;	
		((implant\$7 and bubble and calibrat\$5) and silicon) not	DERWENT;	
		((implant\$7 and bubble and calibrat\$5) and	IBM_TDB	
		semiconductor) not (((implant\$7 and blister and		
		calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister		
		and substrate and semiconductor)		
35	342	438/517	USPAT;	2004/09/10 15:45
33	312	130/317	US-PGPUB;	200407/10 13.43
			EPO;	
			DERWENT;	
			IBM TDB	
36	9	438/517 and (blister\$4 or bubbl\$4)	USPAT;	2004/09/10 15:45
		(	US-PGPUB;	200 400,10 10.12
			EPO;	
			DERWENT;	
			IBM_TDB	
37	6	(438/517 and (blister\$4 or bubbl\$4)) not (438/515 and	USPAT;	2004/09/10 15:45
		(blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or	US-PGPUB;	
		bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not	EPO;	
		(438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7	DERWENT;	
		and bubble and calibrat\$5) and silicon) not ((implant\$7	IBM_TDB	
,		and bubble and calibrat\$5) and semiconductor) not		
		(((implant\$7 and blister and calibrat\$5) not (implant\$7		
		and blister and substrate and semiconductor)) and		
		silicon) not (implant\$7 and blister and substrate and semiconductor)		:
38	147	438/518	USPAT;	2004/09/10 15:45
30	'''	130/310	US-PGPUB;	2004/09/10 13:43
			EPO;	
			DERWENT;	
			IBM TDB	
39	7	438/518 and (blister\$4 or bubbl\$4)	USPĀT;	2004/09/10 15:45
		·	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
40	4	(438/518 and (blister\$4 or bubbl\$4)) not (438/517 and	USPAT;	2004/09/10 15:46
		(blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or	US-PGPUB;	
		bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not	EPO;	
		(438/510 and (blister\$4 or bubbl\$4)) not (438/530 and	DERWENT;	
		(blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and	IBM_TDB	
		calibrat\$5) and silicon not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and		
		blister and calibrat\$5) not (implant\$7 and blister and		
		substrate and semiconductor)) and silicon) not		
		(implant\$7 and blister and substrate and semiconductor)		
41	308	438/522	USPAT;	2004/09/10 15:45
			US-PGPUB;	_00 , 07, 10 13.13
			EPO;	
			DERWENT;	
			IBM_TDB	
42	7	438/522 and (blister\$4 or bubbl\$4)	USPĀT;	2004/09/10 15:45
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	

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4			2004/09/10 15:57
		IPM-IDP	
1050		LICDATE	0004/00/10 15 40
1938	438/\$3 and imaging and (ion or implant\$4)	1	2004/09/10 15:49
		1	
157	(429/\$5 and imaging and (ion on implant \$41) and		2004/00/10 15 40
13/		1 '	2004/09/10 15:49
	(blistera or bubblas)		
155	((438/\$5 and imaging and (ion or implant\$4)) and		2004/09/10 15:57
155		1	200 <del>4</del> /09/10 13:37
		1	
		1 '	
		1	
		IDM_IDB	
	• •		
}			
ا م	•	LISPAT	2004/09/10 16:13
			2004/09/10 16:13
			2004/09/10 16:18
	"5554567"   "5694207"   "5716673"   "6121130").PN.	USIAI	4007/07/10 10:10
	1958 157 155	(blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not ((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and semiconductor)) and silicon) not (implant\$7 and blister and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)  438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)  ((438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)) not (438/522 and (blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not ((implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor))  20040152250.URPN. 6248661.URPN. ("4493855"   "5223443"   "5370969"   "5394006"	(blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not ((implant\$7 and blister and calibrat\$5) and semiconductor) and silicon) not (implant\$7 and blister and semiconductor) and silicon) not (implant\$7 and blister and semiconductor) and silicon) not implant\$4)  157  (438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)  ((438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)) not (438/522 and (blister\$4 or bubbl\$4)) not (438/518 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/516 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not (implant\$7 and blister and substrate and semiconductor) and silicon) not (implant\$7 and blister and substrate and semiconductor) and silicon) not (implant\$7 and blister and substrate and semiconductor) and silicon) not (implant\$7 and blister and substrate and semiconductor) and silicon) not (implant\$7 and blister and substrate and semiconductor)  0 20040152250.URPN.  8 ("4493855"   "5223443"   "5370969"   "5394006"   USPAT USPAT